

10 9 8 7 6 5 4 3 2 1

F

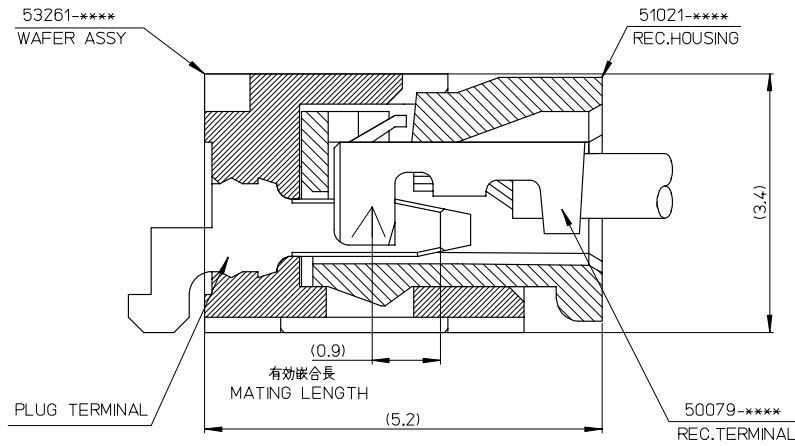
E

D

C

B

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI CHKD: YMAEDA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-T-O-B CONN. 51021,53261 MATING CROSS SECTION		
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002		
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		
0	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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Rev. D 2004/04/02

9

8

7

6

5

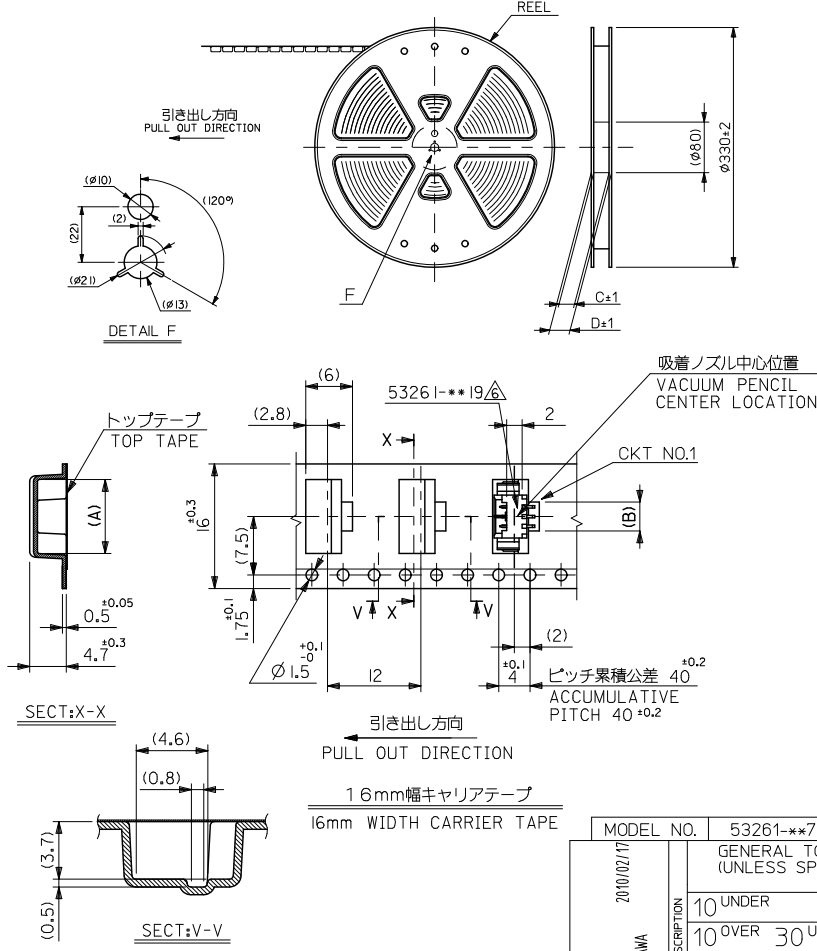
4

3

2

EN-02JA(021)

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**注記 NOTES**

- 53261-\*\*\*19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  

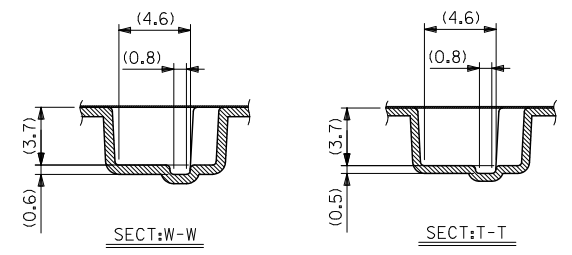
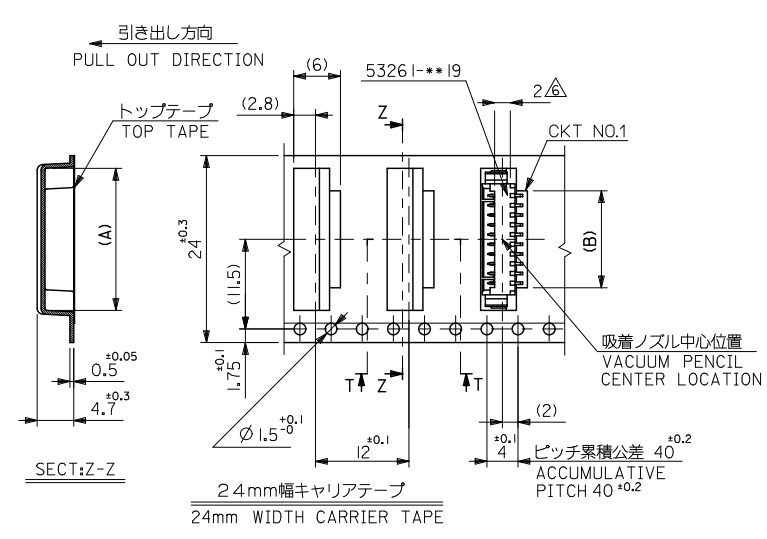
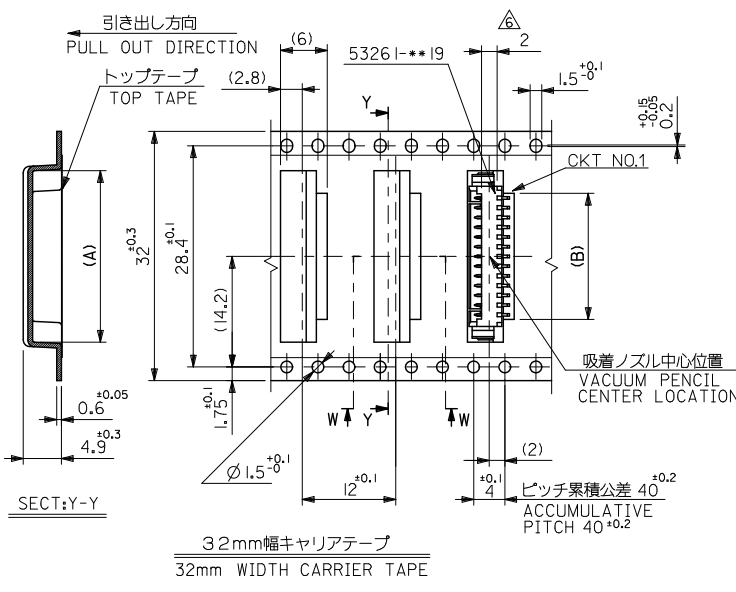
トップテープリーダー部 TOP TAPE LEADER PART	トップテープ未接着部 TOP TAPE NON-BONDED PART
175 <sup>+25</sup>	25 <sup>+5</sup>

- 材料 (MATERIAL)  
 キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
 トップテープ (TOP TAPE): PET, PE, PEF  
 リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-\*\*\*90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*\*90
- ELV 及び RoHS 適合品  
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	3.7	9.5	53261-0371	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	53261-0271	2

MODEL NO.	53261-***71	DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	
EC NO:	D	10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/06	MOLEX INCORPORATED	
DRWNGOTO	CHYDKASAKANA	10 OVER 30 UNDER ±0.25	APPROVED BY NUKITA	DATE 2010/02/18	DOCUMENT NO. SD-53261-023	
APPR:		30 OVER ±0.3	MATERIAL NO.	SEE TABLE & SHEET 2,3	SHEET NO. 1 OF 3	
REV:		ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

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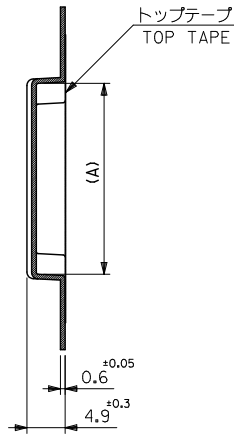


32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75		-1271
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

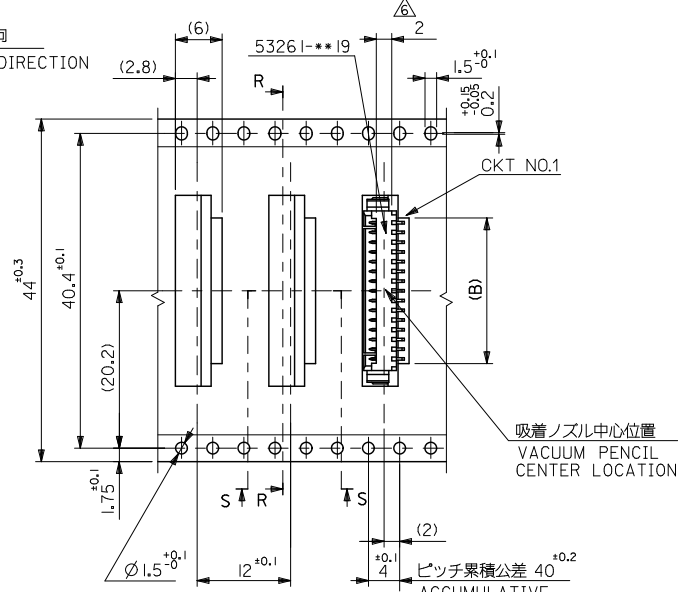
MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.
REVISIONS	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
REV	DESCRIPTION	10 UNDER ±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
		10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE '04/02/06				
		30 OVER ±0.3	APPROVED BY NUKITA	DATE 2010/02/18	MOLEX INCORPORATED			
		ANGULAR ±3 °	MATERIAL NO.	SEE TABLE & SHEET 13	DOCUMENT NO.	SD-53261-023	SHEET NO. 2 OF 3	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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引き出し方向  
PULL OUT DIRECTION

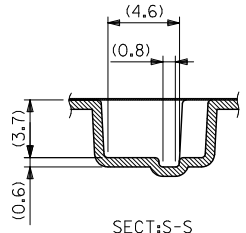


SECT:R-R



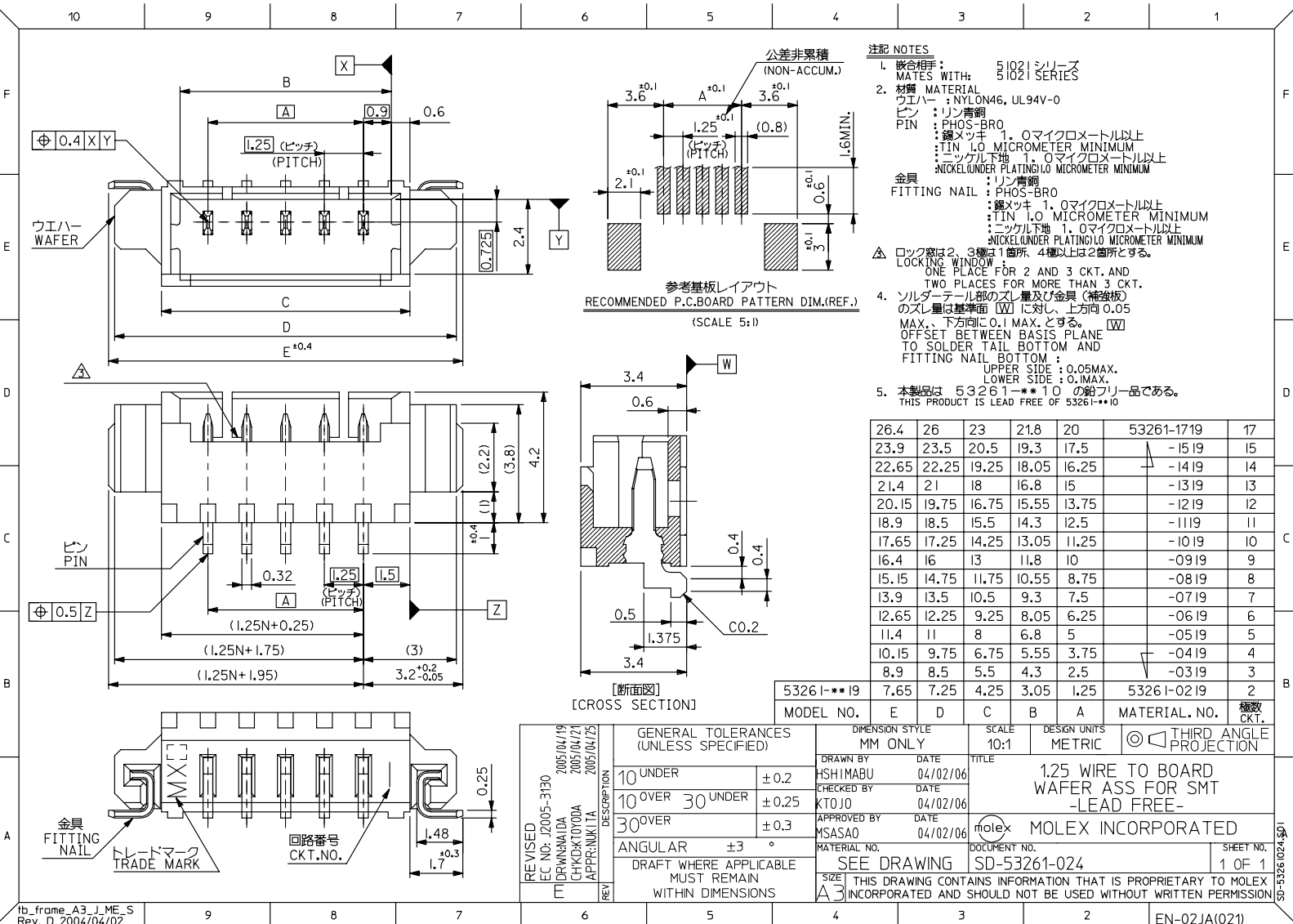
44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

ピッチ累積公差 40<sup>+0.2</sup>  
ACCUMULATIVE PITCH 40<sup>+0.2</sup>



SECT:S-S

MODEL NO.	53261-**-71	44	49.4	45.4	18.7	24.5	53261-1571	15
		キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	53261-1471	14
			EMBOSSED TAPE PACKAGE		極数			
			ORDER NO.		ORDER NO.			
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO:	DRWNYGOTO	10 UNDER	±0.2	MM ONLY		---	METRIC	
DRWNYGOTO	CHYDKASAKANA	10 OVER 30 UNDER	±0.25	DRAWN BY DATE		TITLE		
CHYDKASAKANA		30 OVER	±0.3	H. SHIMABUKUR '04/02/06		1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
		ANGULAR	±3 °	CHECKED BY DATE		MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		K. TOJO '04/02/06		SD-53261-023		
				APPROVED BY DATE		SHEET NO.		
				NUKITA 2010/02/18		3 OF 3		
				MATERIAL NO.		DOCUMENT NO.		
				SEE TABLE & SHEET 12				
				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



- 注記 NOTES
- 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
  - 材質 MATERIAL: NYLON46, UL94V-0  
ピン: リン青銅  
PIN: PHOS-BRO  
: 銅メッキ 1.0マイクromメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0マイクromメートル以上  
: NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM  
金具: リン青銅  
FITTING NAIL: PHOS-BRO  
: 銅メッキ 1.0マイクromメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0マイクromメートル以上  
: NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
  - ロック窓は2, 3個は1箇所、4個以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
  - ソルダーテール部のスリ量及び金具(補強材)のスリ量は基準面 [W] に対し、上方向 0.05 MAX、下方向に 0.1 MAX とする。 [W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
  - 本製品は 53261-\*\*-\*\*10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-\*\*10

26.4	26	23	21.8	20	53261-1719	17
23.9	23.5	20.5	19.3	17.5	-1519	15
22.65	22.25	19.25	18.05	16.25	-1419	14
21.4	21	18	16.8	15	-1319	13
20.15	19.75	16.75	15.55	13.75	-1219	12
18.9	18.5	15.5	14.3	12.5	-1119	11
17.65	17.25	14.25	13.05	11.25	-1019	10
16.4	16	13	11.8	10	-0919	9
15.15	14.75	11.75	10.55	8.75	-0819	8
13.9	13.5	10.5	9.3	7.5	-0719	7
12.65	12.25	9.25	8.05	6.25	-0619	6
11.4	11	8	6.8	5	-0519	5
10.15	9.75	6.75	5.55	3.75	-0419	4
8.9	8.5	5.5	4.3	2.5	-0319	3

53261-**-**19	7.65	7.25	4.25	3.05	1.25	53261-0219	2
MODEL NO.	E	D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2005-3130 DRAWN BY: CHIKAKIYODA CHKD BY: KYODA APPR: NUKITA 2005/04/19 2005/04/21 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR	±3 °	MATERIAL NO. SEE DRAWING	SIZE A3	SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					EN-02JA(021)